CLAIMS

[Claim 1]

A resin film-forming sheet to be stuck to a silicon wafer to form a resin film on the silicon wafer, which comprises a polymer component (A) comprising an acrylic polymer (A1) having a glass transition temperature (Tg) of −40 to 0° C, wherein:

the surface roughness (Ra) of the surface (α) of the sheet on the side to be stuck to a silicon wafer is 40 nm or more.

[Claim 2]

The resin film-forming sheet according to claim 1, which comprises a curable component (B).

[Claim 3]

The resin film-forming sheet according to claim 2, wherein the glass transition temperature (Tg) of the acrylic polymer (A1) is −40 to −10.1° C.

[Claim 4]

The resin film-forming sheet according to any one of claims 1 to 3, which comprises a heat-curable component (B1).

[Claim 5]

The resin film-forming sheet according to any one of claims 1 to 4, which comprises a filler (C).

[Claim 6]

The resin film-forming sheet according to claim 5, wherein the content of the filler (C) is 10 to 80% by mass relative to the total amount of the resin film-forming sheet.

[Claim 7]

The resin film-forming sheet according to claim 5 or 6, wherein the mean particle size of the filler (C) is 100 to 1000 nm.

[Claim 8]

The resin film-forming sheet according to any one of claims 1 to 7, which is a protective film-forming sheet for forming a protective film on a silicon wafer.

[Claim 9]

The resin film-forming sheet according to any one of claims 1 to 8, wherein, after the surface (α) of the resin film-forming sheet is stuck to a silicon wafer, the gloss value measured from the surface (β') opposite to the silicon wafer of the resin film formed from the resin film-forming sheet is 25 or more.

[Claim 10]

A resin film-forming composite sheet comprising the resin film-forming sheet of any one of claims 1 to 9 and a support.

[Claim 11]

A resin film-forming composite sheet according to claims 10, wherein comprising a configuration in which the surface (α) of the resin film-forming sheet on the side to be stuck to a silicon wafer and the surface (i) of the support (I) having a surface roughness of 40 nm or more are directly laminated.

[Claim 12]

A resin film-forming composite sheet comprising a resin film-forming sheet, which is to be stuck to a silicon wafer to form a resin film on the silicon wafer and comprises a polymer component (A) comprising an acrylic polymer (A1) having a glass transition temperature (Tg) of −40 to 0° C, and a support (I), and further comprising a configuration in which the surface (α) of the resin film-forming sheet on the side to be stuck to a silicon wafer and the surface (i) of the support (I) having a surface roughness of 40 nm or more are directly laminated.

[Claim 13]

The resin film-forming composite sheet according to claim 12, wherein the surface roughness (Ra) of the surface (α) of the resin

film-forming sheet exposed when the support (I) is removed from the resin film-forming composite sheet is 40 nm or more.

[Claim 14]

The resin film-forming composite sheet according to claim 12 or 13, wherein the resin film-forming sheet comprises a heat-curable component (B1).

[Claim 15]

The resin film-forming composite sheet according to claim 12 or 13, which has a configuration in which a second support (II) is further laminated directly on the surface (β) opposite to the surface (α) of the resin film-forming sheet, and in which the resin film-forming sheet contains the heat-curable component (B1).

[Claim 16]

The resin film-forming composite sheet according to claim 15, wherein the support (II) is a pressure sensitive adhesive sheet having a pressure sensitive adhesive layer, and the pressure sensitive adhesive layer is directly laminated on the surface (β) of the resin film-forming sheet.